

Abstract Deadline Extended: April 17, 2009

IMAPS 2009 Symposium - Call for Papers

Bringing Together the Entire Microelectronics Supply Chain!

San Jose Convention Center, San Jose, California - USA

November 1 - 5, 2009

The 42nd International Symposium on Microelectronics will be held at the San Jose Convention Center, San Jose, California - USA and is being sponsored by the International Microelectronics And Packaging Society (IMAPS). The IMAPS Technical Committee seeks original papers that present progress on technologies “*between the chip and the system*”. The 42nd Symposium on Microelectronics will cover four tiers of electronics: Industry, Systems & Applications, Design, and Materials & Process. Abstracts should highlight the major contributions of the work in one or more of these four areas. All abstracts submitted must represent original, previously unpublished work.

General Chair:

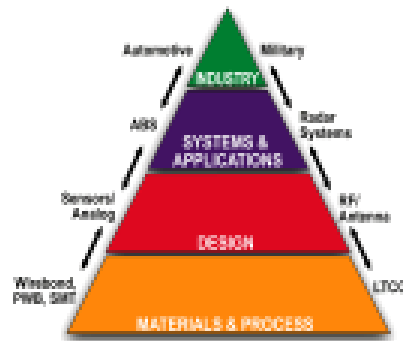
Jeff Demmin, Tessera Inc.
jdemmin@tessera.com

Technical Program Chair:

Jie Xue, Cisco Systems
jixue@cisco.com

Technical Program Co-Chairs:

Ricky Lee, Hong Kong Univ. of Science & Technology rickylee@ust.hk	Mark Hoffmeyer, IBM Systems and Technology Group hoffmeyr@us.ibm.com
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Planned Sessions Include

Industry

- ◆ Consumer, Portable, and Wireless
- ◆ Biomedical
- ◆ Telecom
- ◆ Defense and Security
- ◆ Computing and Gaming
- ◆ Automotive, Industrial, Harsh Environment Electronics Applications
- ◆ Solar and Alternative Energy

Systems & Applications

- ◆ Thermal Management
- ◆ Power Management
- ◆ Cost Reduction, Outsourcing and Supply Chain Management
- ◆ Electromagnetic Interference (EMI)
- ◆ Sensors and Nano Packaging
- ◆ Emerging Technologies
- ◆ System Packaging
- ◆ Microwave & RF Applications
- ◆ Electrostatic Discharge (ESD) Protection
- ◆ Photonic / Optoelectronic Packaging
- ◆ Packaging for Extreme Environments
- ◆ MEMS Packaging
- ◆ LED Packaging
- ◆ Packaging of Compound Semiconductor Devices

Translated (Invited Speakers Only)

- ◆ Japanese (Japanese to English translation)

Poster Session (Interactive Forum)

Outstanding papers that do not fit in planned or created sessions will be considered for the interactive poster session.

Please send your 250-300 word abstract **electronically only** using the on-line submittal form at: www.imaps.org/abstracts.htm

Abstract Cut-off Date Extended: April 17, 2009

Notice of Acceptance: May 15, 2009

Final Manuscript Due: September 4, 2009

All Speakers are required to register for the symposium, but at a reduced registration fee in recognition of their contribution to the event.

Cash Awards Offered: \$2000 for Best Paper of Symposium; \$500 each for two Outstanding Papers of Symposium.

Accepted papers may be considered for publication in the IMAPS Journal of Microelectronics and Electronic Packaging.

If you need assistance with the on-line submission form, please email Jackki Morris-Joyner (jmorris@imaps.org) or call 305-382-8433.

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Design

- ◆ Electrical Modeling, Signal & Power Integrity
- ◆ High Performance Interconnects and Boards
- ◆ 3D Packaging Approaches
- ◆ Embedded and Integrated Passives
- ◆ Wafer Level Packaging / CSP
- ◆ Advanced Materials

Materials and Process

- ◆ Flip-Chip and Wafer Bumping Processes and Reliability
- ◆ Underfill/Encapsulants, and Adhesives
- ◆ Pb-Free Solder Materials, RoHS, Processes, and Reliability
- ◆ Design for Reliability
- ◆ Package Reliability Testing
- ◆ Wirebonding and Stud Bumping
- ◆ Ceramic and LTCC Packaging
- ◆ Substrate Materials and Technology
- ◆ Printed Electronics

Invited Session on Intelligent Uses of Precious Metals in Microelectronics

- ◆ Uses of Precious Metals in Microelectronics
 - ◆ Recovery/Recycling/Refining
 - ◆ Precious Metal Trading
 - ◆ Future Outlook for Precious Metal Prices
 - ◆ Cost Savings Techniques and Technologies
 - ◆ Leasing and Pool Accounts
 - ◆ Advantages of Precious Metals over non Precious Metals
 - ◆ Substitute Materials
 - ◆ Volume Reduction (diameter, thickness, etc.)
 - ◆ New Applications using Precious Metals
- Visit www.imaps.org/preciousmetals for more information.